

# *Cool Silicon for Europe*

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Starting Point: Cool Silicon Overview

Relevant Trends

Priorities for the Call

Summary

## Starting Point: Cool Silicon Overview

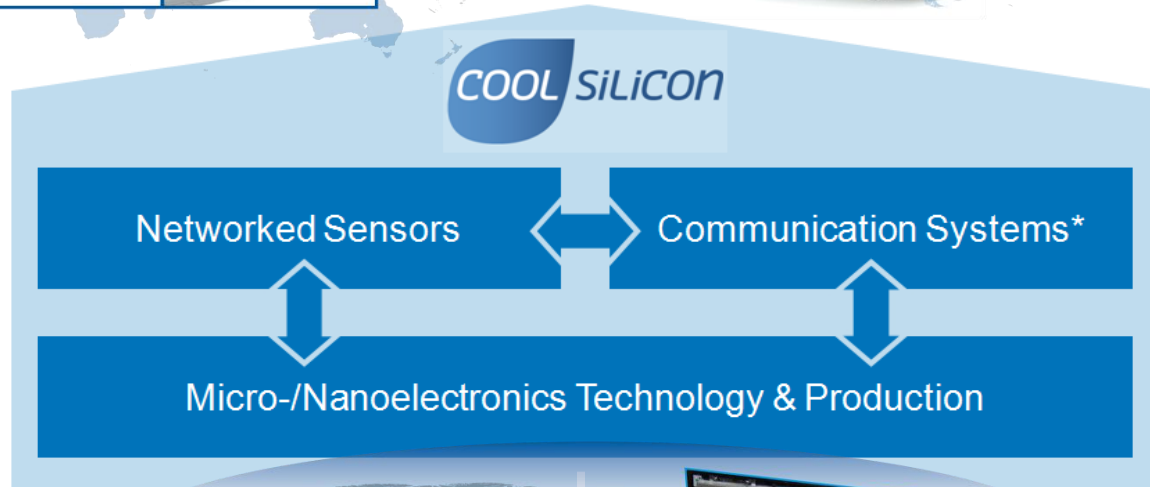
Relevant Trends

Priorities for the Call

Summary

- The world wide usage of electronic devices will keep on growing for many more years to come
- This development is only sustainable if the total energy consumption of electronic devices is kept at a constant level
- As a result the energy efficiency of electronic devices needs continuous and significant improvement
- Cool Silicon is working in all areas of the value chain to make the constant energy reduction in electronics an integral part of the design and fabrication process of electronic devices.  
Because Saxony has a leading role in this area this focus offers a competitive advantage for the cluster partners

# Project Overview – technical projects



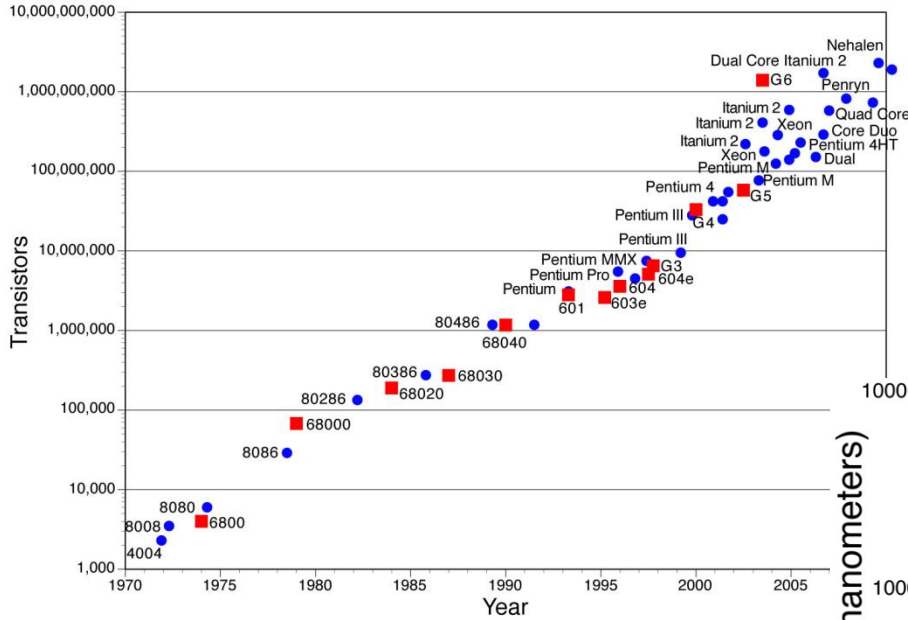
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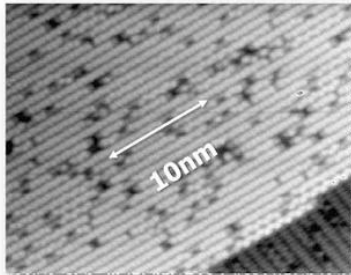
Summary

# Relevant Trends – Moore's Law

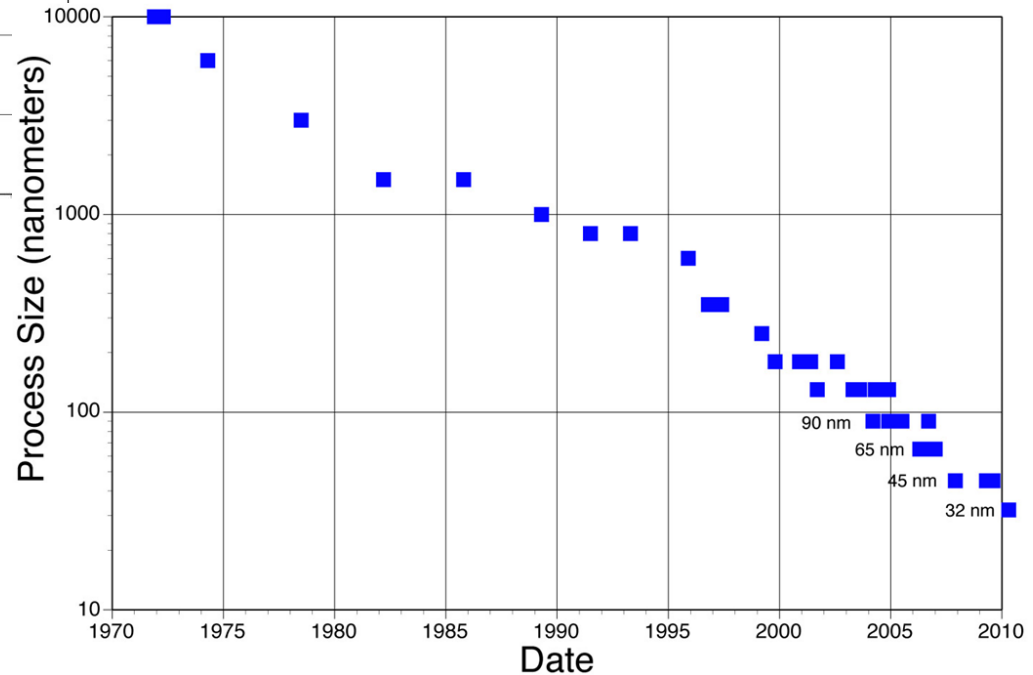


- The success of semiconductor technology is based on the continuous scaling of minimum feature sizes
- Scaling is connected to higher energy efficiency

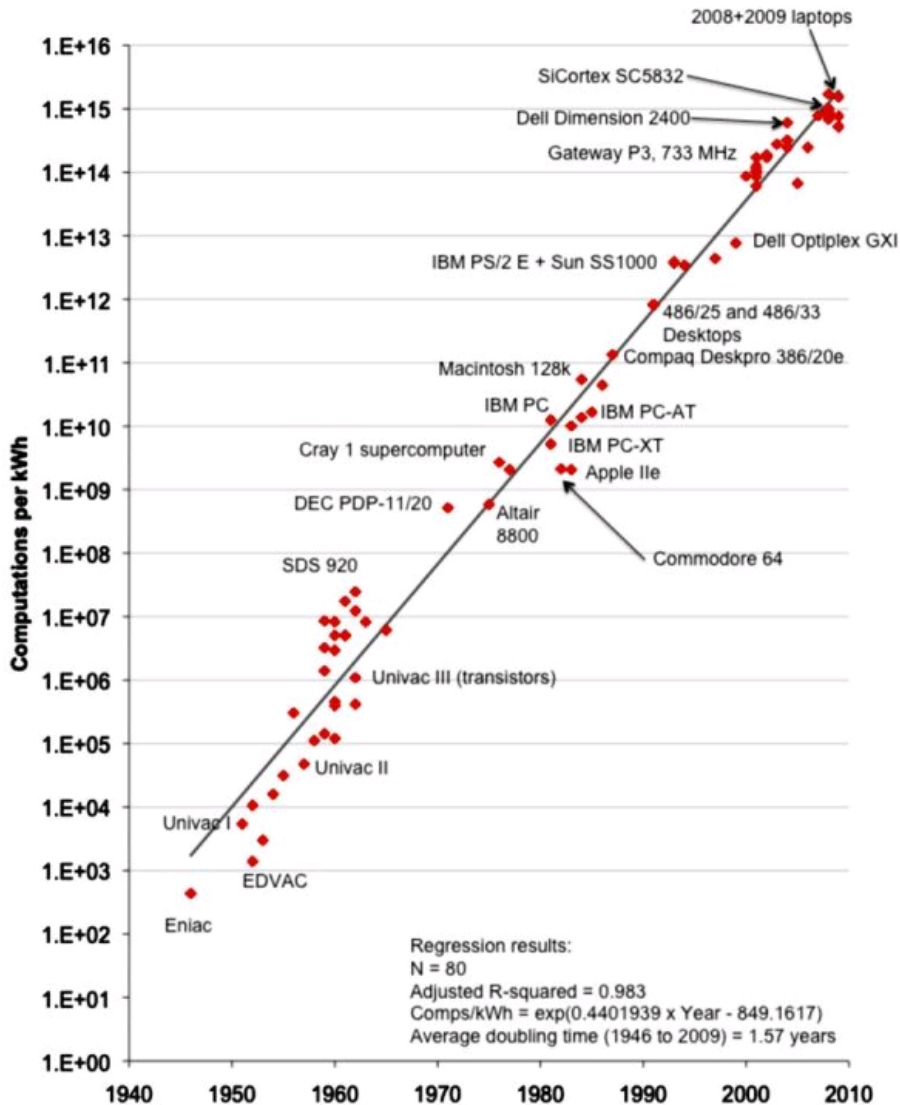
Scaling: Approaching Atomic Dimensions



Scanning tunneling microscope image of a silicon surface showing 10nm is ~20 atoms across



# Relevant Trends – Moore's Law

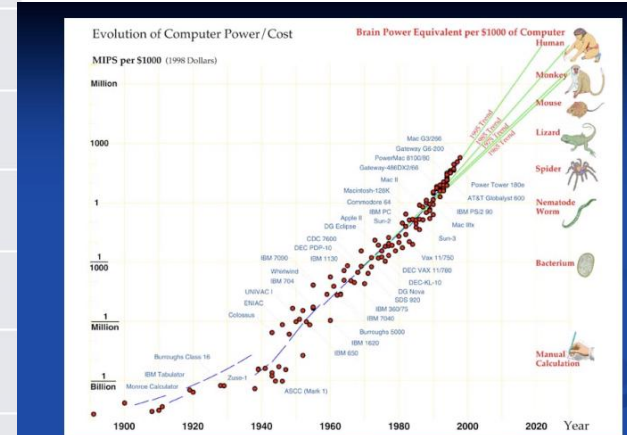
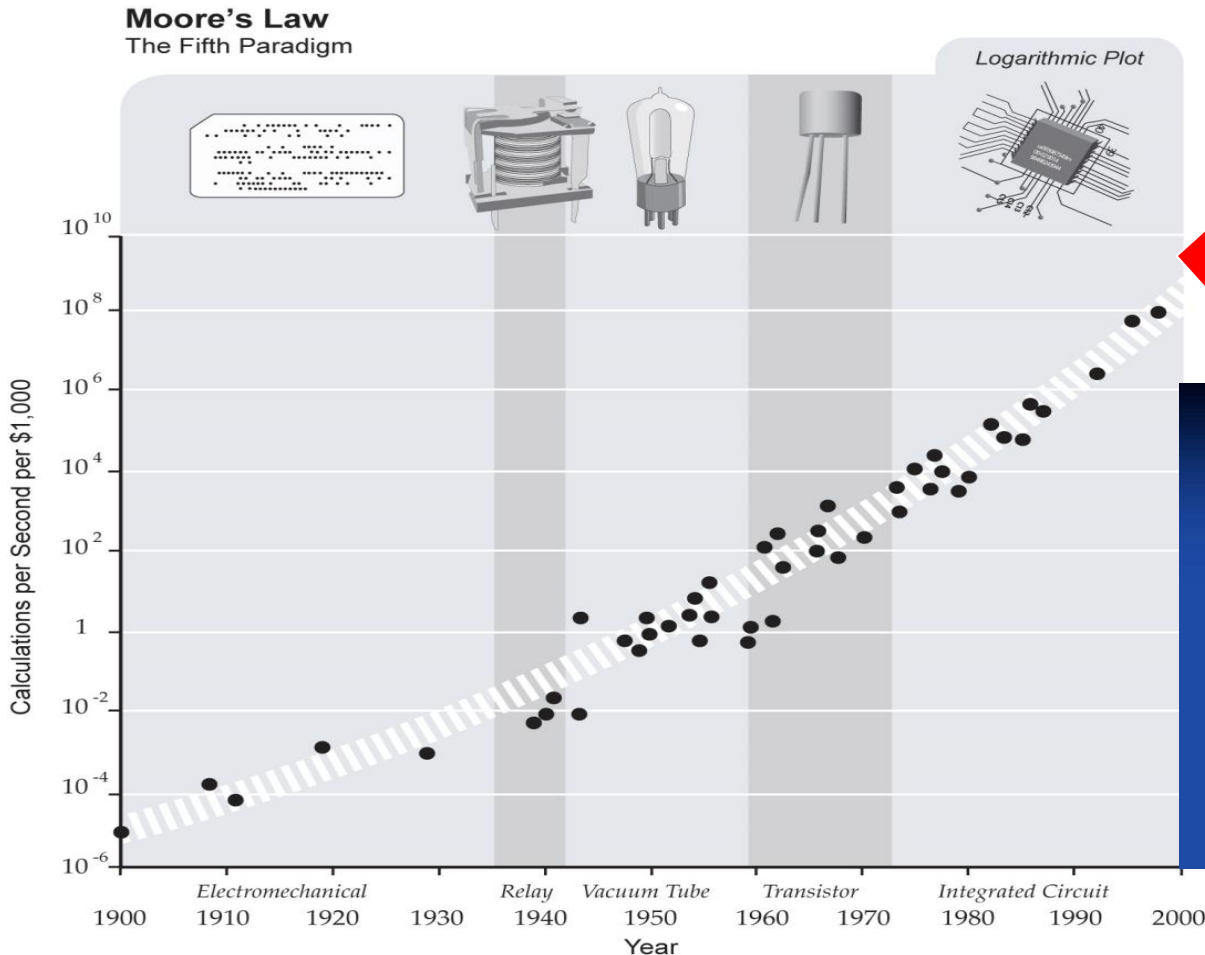


■ Need for even stronger energy efficiency trend to keep total power consumption constant



# Relevant Trends – the sixth paradigm

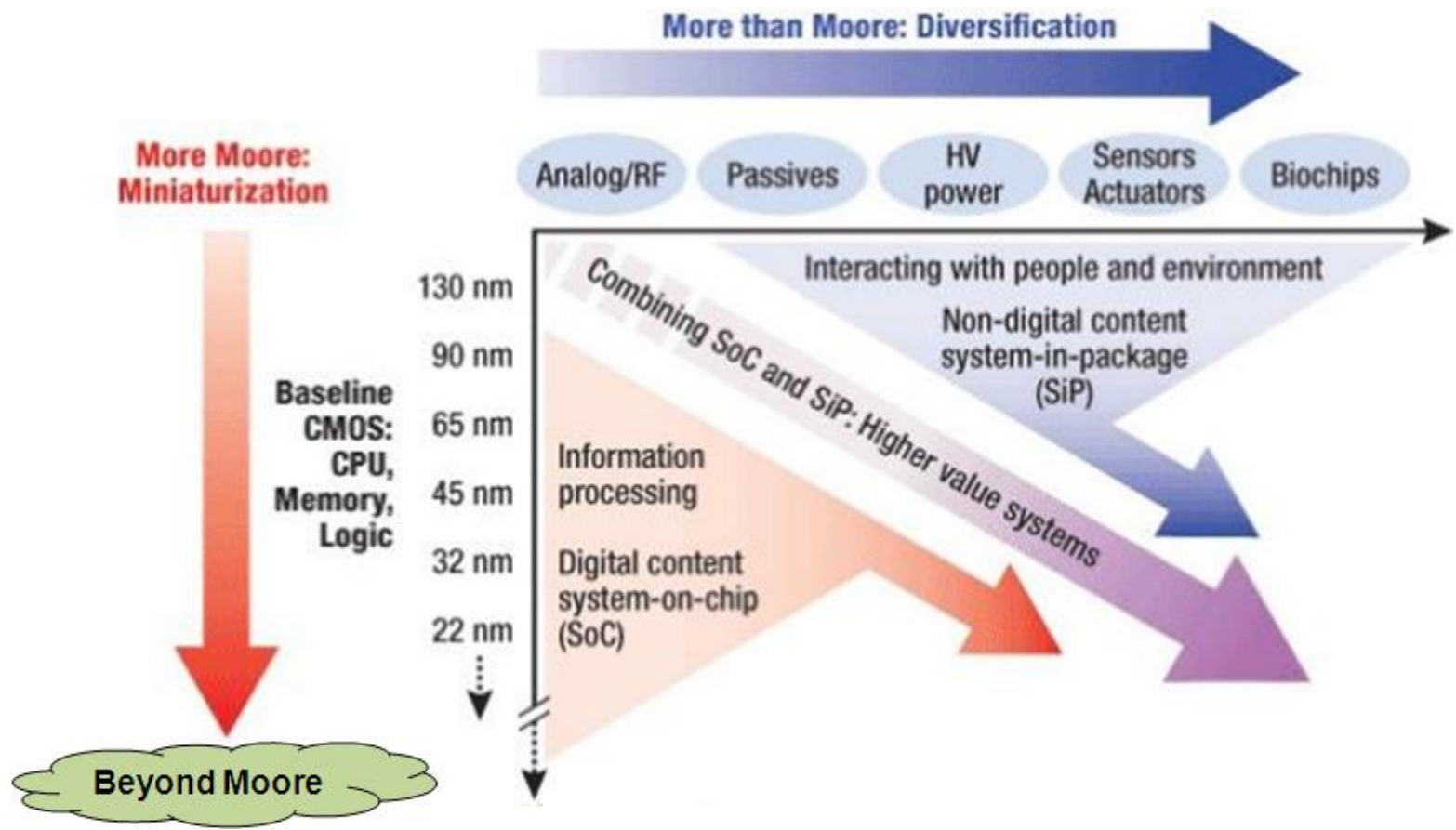
- Exponential growth did start long before IC technology!
- It is likely that (exponential) growth will expand beyond IC technology



# Relevant Trends – More than Moore



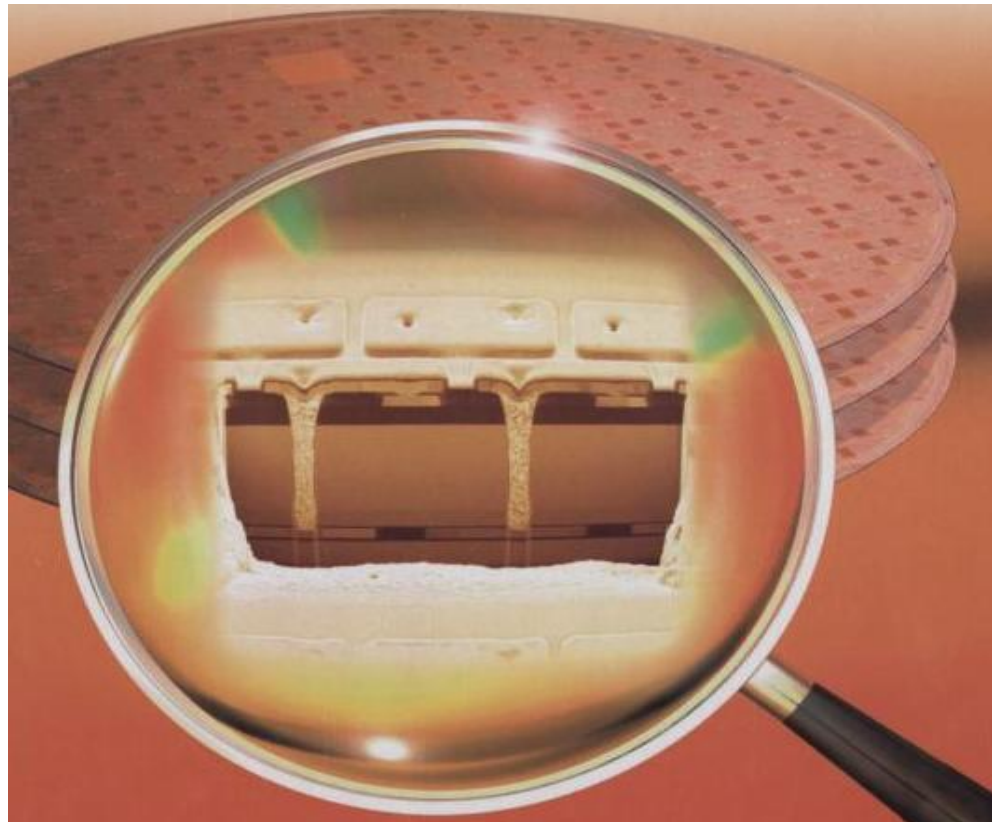
- New Functions are added to silicon!
- Power electronics can help to increase energy efficiency of many systems



# Relevant Trends – 3D Integration



- 3<sup>rd</sup> dimension allows to increase complexity beyond Moore's Law
- Cost and performance effective heterogenous integratio of independently optimized technologies



- Moore's Law is dominating the energy efficiency trend during the last 45 years
  - However: Optimization was mostly towards more performance
  - ➔ Total power consumption is increasing exponentially
- Need to maintain cost scaling, performance improvement and energy efficiency improvement after scaling stops in about one decade
- Need to enhance energy efficiency beyond the conventional scaling trends
- What after Moore?
  - New disruptive technology?
  - 3D integration?
  - something else?

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- New disruptive device technologies
- Needs to clearly show the potential improvement compared to the ultimate CMOS device

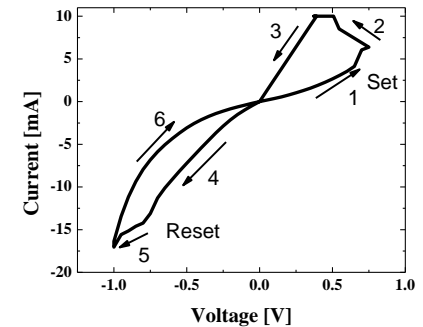
- Possibilities:

Reconfigurable Devices and wiring  
e.g. electrical polarity control  
memristive devices

- Nonvolatile Memory Devices

- ✓ High density data storage: Large potential for data centers etc.
- ✗ However: only little industrial activity left in Europe  
e.g. resistive switching HDDS is investigated by leading industry players with large resources
- ✓ embedded Memories

- Energy efficient 3D Systems



- Make systems adaptive:

1. sense, 2. adjust, 3. supply

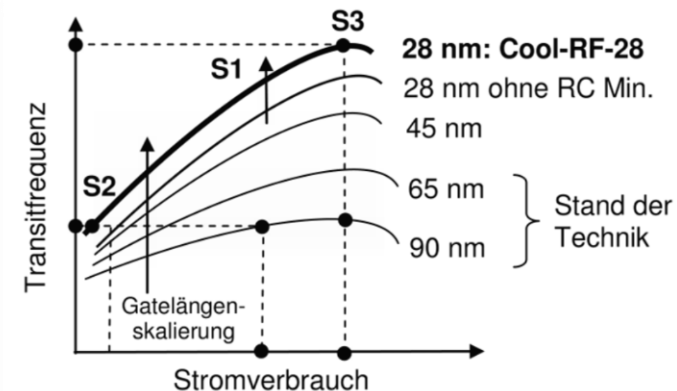
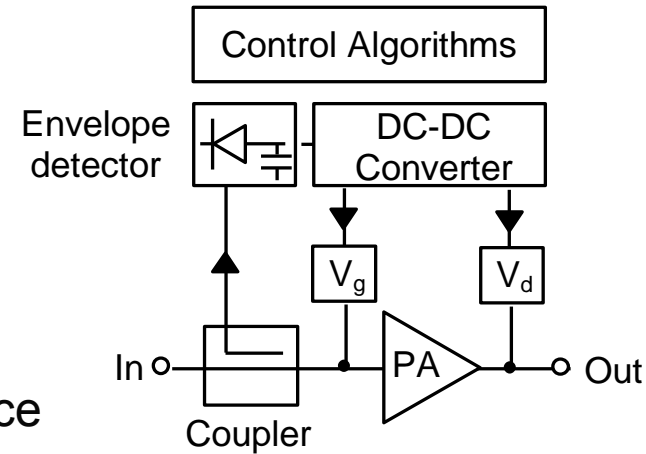
e.g. regarding data rates/bandwidth, clock frequency, supply current & voltage,

“Real-time” control very efficient, challenging for device speed and system stability

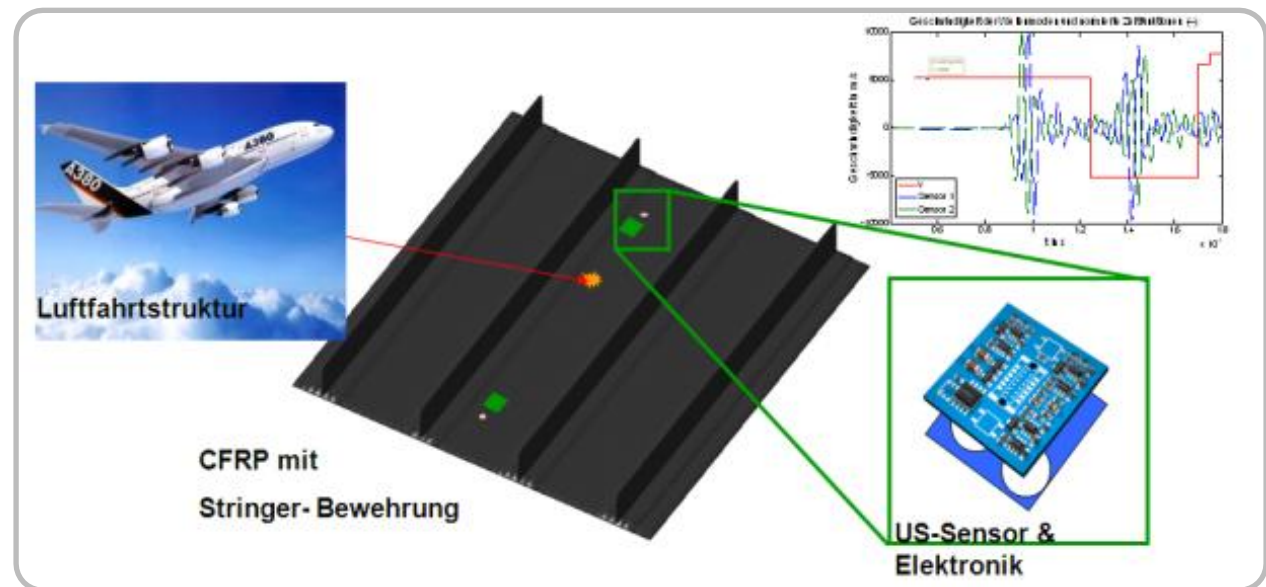
Challenge: Low distortions

- Smart hierarchical stand-by and wake-up functions

- Make extensive use of benefit of Moore’s for energy efficiency



- Energy harvesting concepts for autonomous sensor systems
- Depends on application scenario





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## Technical Topics

- New Device Concepts enabling reconfigurability
- Design solutions including adaptivity, sleep and wake up
- Energy harvesting concepts for autonomous sensors to enable cyber physical systems

## General Aspects

- System design is crucial:  
Interdisciplinary has to mean that all levels from Material to system (including software) have to be interconnected
- Energy efficiency has to be established as a boundary condition for system design that is as important as performance and cost
- include education

# Thank you for your attention!



# BACKUP

# Project Overview

## Area I: Micro- und Nanotechnology



# Project Overview – Phase

## Area II: Communication Technology



### Mobile

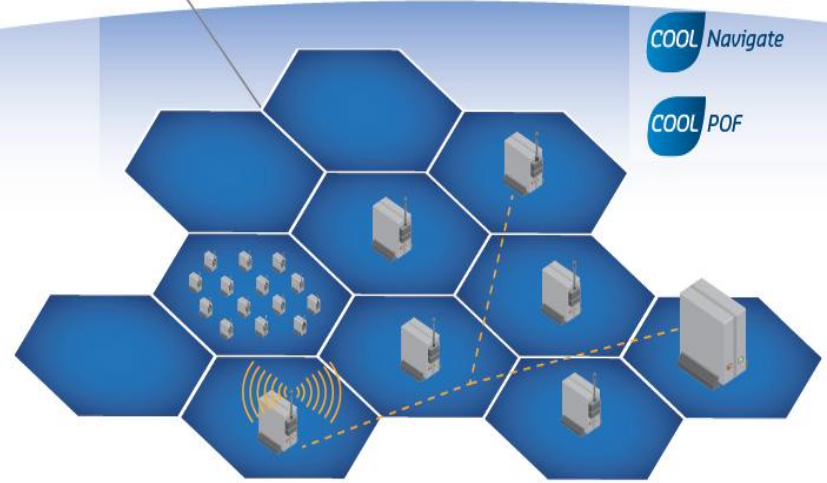
Phase 1 >>> Phase 2

- COOL BaseStations
- COOL Cellular
- COOL Software
- COOL Relay
- COOL RF 28

### Smart Mobile Devices

Phase 1 >>> Phase 2

- COOL Reader
- COOL MES
- COOL Navigate
- COOL POF



### Car Communication

Phase 1 >>> Phase 2

- COOL Energy Car Communication
- COOL Car
- COOL Digital Radio

### Digital Radio and TV

Phase 1 >>> Phase 2

- COOL Repeater
- COOL Digital Radio
- COOL Wireless Audio





# Project Overview – Area III: Networked Sensors



## System Design

Phase 1

COOL SAW

COOL Sensornet

COOL Sens

COOL ConSens

## Energy Harvesting

Phase 1

COOL Sensornet

Phase 2

COOL Maintenance

COOL Network Planning

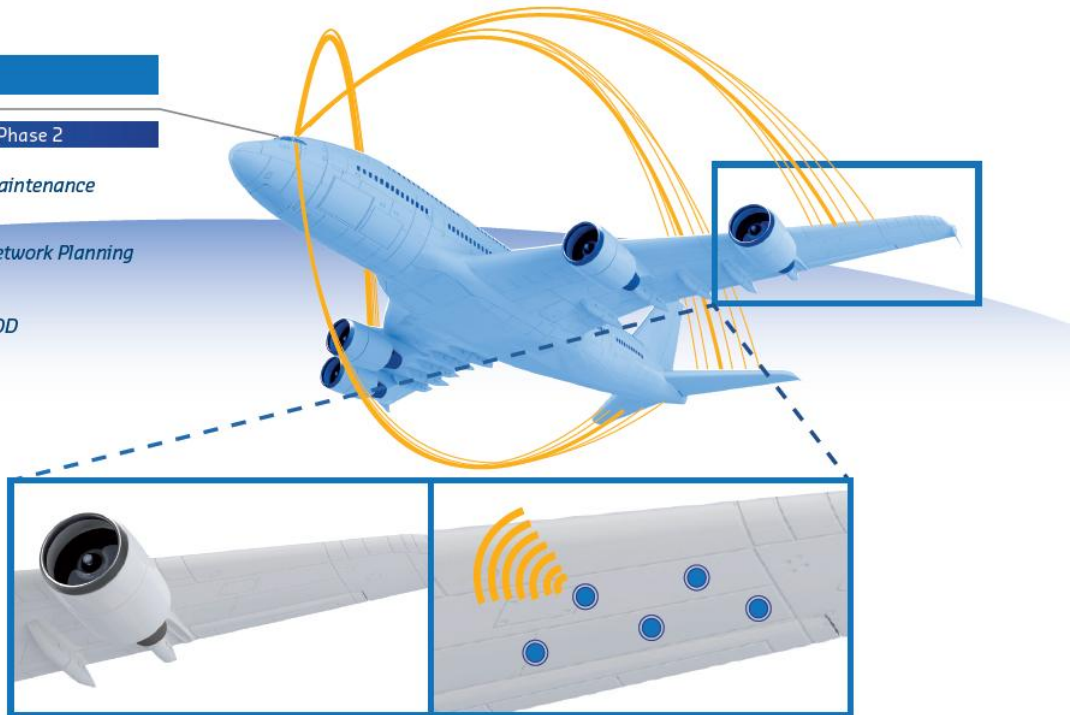
COOL POD

## System Integration

Phase 1

COOL Sensor Integration

COOL Sensor Implement



## Applications

Phase 2

COOL Display

COOL RailSens

COOL Energy Car Communication

COOL Tool

COOL Public Transport Information

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